



Material Content Data Sheet



Sales Product Name		BSZ058N03MS G		Issued		25. January 2018		
MA#		MA001786822						
Package		PG-TSDSON-8-2		Weight*		39.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.076	2.71	2.71	27134	27134
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53	
	non noble metal	zinc	7440-66-6	0.008	0.02		211	
	non noble metal	iron	7439-89-6	0.168	0.42		4226	
wire	non noble metal	copper	7440-50-8	6.808	17.16	17.61	171600	176090
	non noble metal	copper	7440-50-8	0.043	0.11	0.11	1094	1094
	organic material	carbon black	1333-86-4	0.038	0.10		959	
encapsulation	plastics	epoxy resin	-	1.960	4.94		49401	
	inorganic material	silicondioxide	60676-86-0	17.029	42.92	47.96	429259	479619
leadfinish	non noble metal	tin	7440-31-5	0.387	0.98	0.98	9759	9759
plating	noble metal	silver	7440-22-4	0.963	2.43	2.43	24264	24264
solder	non noble metal	tin	7440-31-5	0.026	0.07		660	
	noble metal	silver	7440-22-4	0.033	0.08		825	
	non noble metal	lead	7439-92-1	1.250	3.15	3.30	31503	32988
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.086	0.22		2174	
	non noble metal	copper	7440-50-8	3.501	8.83	9.06	88253	90563
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		48	
	non noble metal	zinc	7440-66-6	0.008	0.02		190	
	non noble metal	iron	7439-89-6	0.151	0.38		3804	
	non noble metal	copper	7440-50-8	6.127	15.44	15.84	154447	158489
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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